

**Date:** April 18, 2024  
**Time:** 12:00 PM ET  
**Presenter:** Jobert van Eisden  
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## Metallization of glass core and through-glass vias

### **Abstract:**

As glass is gaining a lot of attention and momentum as a state of the art semiconductor packaging technology, industry is looking to complete the supply chain to enable this promising technology. Several advances have been made in the field of metallizing glass core through vias, and in today's presentation, we will discuss several options and MKS' take on delivering a manufacturable solution. We will discuss options for seed layer deposition and highlight the MKS wet metallization technique that allows us to directly plate on glass. We will also go over several options for electrolytic plating of the bulk copper conductor for the through glass vias.

### **Bio:**



Jobert van Eisden is the OEM technology exchange director for the Americas. He is located in the Albany, NY region and has been with Atotech, now MKS Instruments for 16 years where he specializes in technology development of wet metallization techniques for semiconductor and advanced packaging applications.

He received his Masters in Physics from SUNY Albany and Doctorate in NanoScience and Engineering from the SUNY Polytechnic institute, specializing in optoelectronics.

He contributes as a subcommittee member to the ECTC assembly and manufacturing technology committee and as track and session chair for the IMAPS conferences.

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**Binghamton Chapter**

